

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak repetitive off-state voltage⁽¹⁾ ($T_J = -40$ to $+125^\circ\text{C}$, gate open)			
MCR218-2		50	
MCR218-3		100	
MCR218-4	V_{DRM}	200	V
MCR218-6	V_{RRM}	400	
MCR218-7		500	
MCR218-8		600	
MCR218-10		800	
On-state RMS current (180° conduction angles, $T_C = 70^\circ\text{C}$)	$I_{\text{T(RMS)}}$	8.0	A
Peak non-repetitive surge current (one half-cycle, sine wave, 60Hz, $T_J = 125^\circ\text{C}$)	I_{TSM}	100	A
Circuit fusing consideration ($t = 8.3\text{ms}$)	I^2t	26	A^2s
Forward peak gate power (pulse width $\leq 1.0\mu\text{s}$, $T_C = 70^\circ\text{C}$)	P_{GM}	5	W
Forward average gate power ($t = 8.3\text{ms}$, $T_C = 70^\circ\text{C}$)	$P_{\text{G(AV)}}$	0.5	W
Forward peak gate current (pulse width $\leq 1.0\mu\text{s}$, $T_C = 70^\circ\text{C}$)	I_{GM}	2.0	A
Operating temperature range	T_J	-40 to +125	$^\circ\text{C}$
Storage temperature range	T_{stg}	-40 to +150	$^\circ\text{C}$

Note 1: V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Thermal resistance, junction to case	$R_{\theta\text{JC}}$	2.0	$^\circ\text{C}/\text{W}$
Maximum lead temperature for soldering purposes 1/8" from case for 10s	T_L	260	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Peak forward or reverse blocking current ($V_{\text{AK}} = \text{Rated } V_{\text{DRM}}$ or V_{RRM} , gate open)	I_{DRM}				
$T_J = 25^\circ\text{C}$	I_{RRM}	-	-	10	μA
$T_J = 125^\circ\text{C}$		-	-	2.0	mA
ON CHARACTERISTICS					
Peak on-state voltage* ($I_{\text{TM}} = 16\text{A}$ peak)	V_{TM}	-	1.5	1.8	V
Gate trigger current (continuous dc) ($V_D = 12\text{V}$, $R_L = 100\Omega$)	I_{GT}	-	10	25	mA
Gate trigger voltage (continuous dc) ($V_D = 12\text{V}$, $R_L = 100\Omega$)	V_{GT}	-	-	1.5	V

MCR218 SERIES

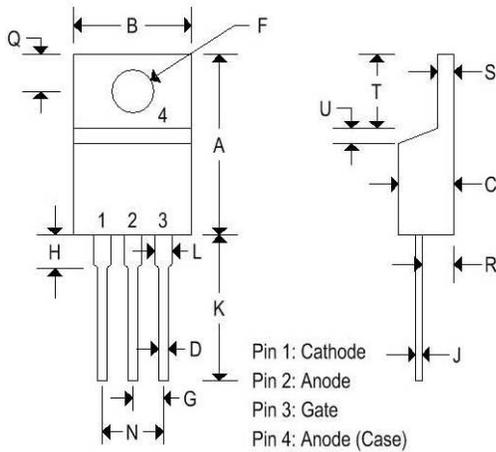
SILICON CONTROLLED RECTIFIERS

Gate non-trigger voltage (Rated 12V, $R_L = 100\Omega$, $T_J = 125^\circ\text{C}$)	V_{GD}	0.2	-	-	V
Holding current ($V_D = 12\text{V}$, initiating current = 200mA, gate open)	I_H	-	16	30	mA
DYNAMIC CHARACTERISTICS					
Critical rate of rise of off-state voltage ($V_D = \text{rated } V_{DRM}$, exponential waveform, gate open, $T_J = 125^\circ\text{C}$)	dv/dt	-	100	-	V/ μs

* Pulse width $\leq 1.0\text{ms}$, duty cycle $\leq 2\%$.

MECHANICAL CHARACTERISTICS

Case:	TO-220AB
Marking:	Body painted, alpha-numeric
Pin out:	See below



	TO-220AB			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.575	0.620	14.600	15.750
B	0.380	0.405	9.650	10.290
C	0.160	0.190	4.060	4.820
D	0.025	0.035	0.640	0.890
F	0.142	0.147	3.610	3.730
G	0.095	0.105	2.410	2.670
H	0.110	0.155	2.790	3.930
J	0.014	0.022	0.360	0.560
K	0.500	0.562	12.700	14.270
L	0.045	0.055	1.140	1.390
N	0.190	0.210	4.830	5.330
Q	0.100	0.120	2.540	3.040
R	0.080	0.110	2.040	2.790
S	0.045	0.055	1.140	1.390
T	0.235	0.255	5.970	6.480
U	-	0.050	-	1.270
V	0.045	-	1.140	-
Z	-	0.080	-	2.030

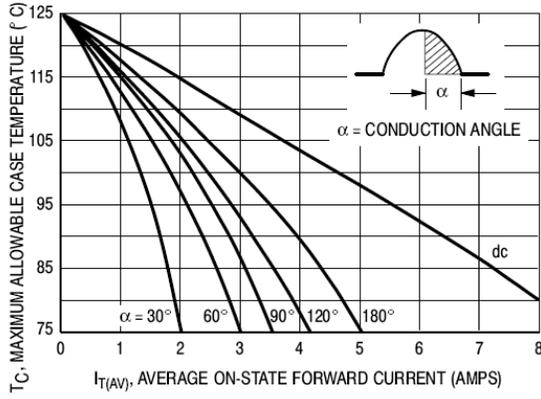


Figure 1. Current Derating

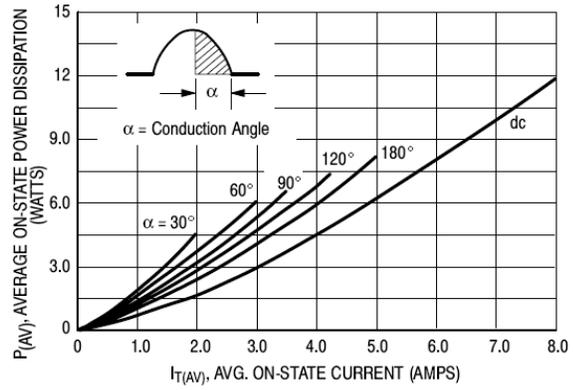


Figure 2. On-State Power Dissipation

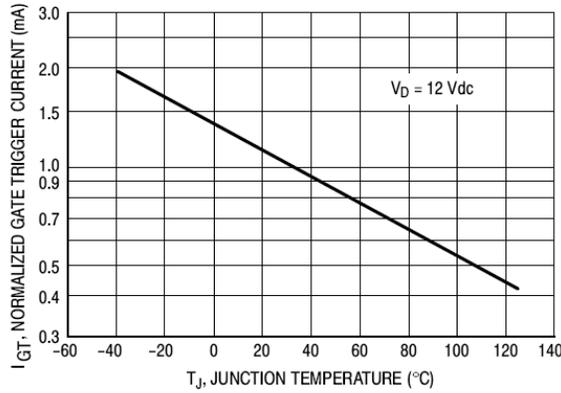


Figure 3. Typical Gate Trigger Current versus Temperature

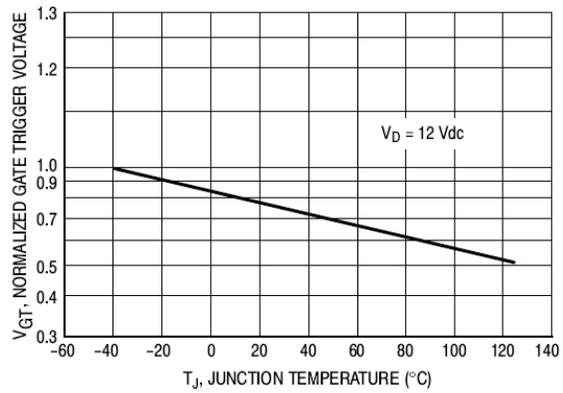


Figure 4. Typical Gate Trigger Voltage versus Temperature

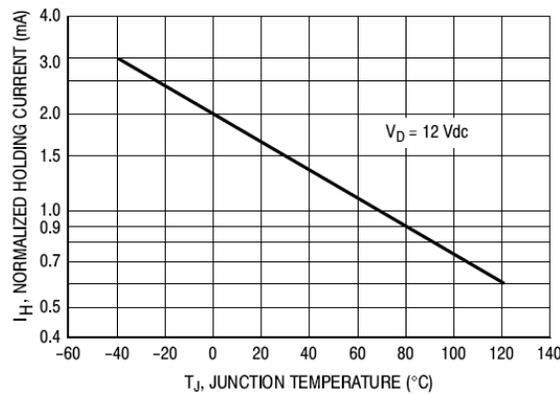


Figure 5. Typical Holding Current versus Temperature